

ELECTRONIC DEVICE TEST APPARATUS

ABSTRACT OF THE DISCLOSURE

An electronic device test apparatus for testing IC chips (IC) by pushing their input/output terminals (HB) against contact units of a test head, provided with an IC moving system (410) for picking up and moving an IC chip (IC) at the front surface where input/output terminals (HB) are led out, a first camera for capturing an image of the front surface of an IC chip (IC) before being picked up, a second camera for capturing an image of a back surface of an IC chip (IC) after being picked up, and an image processing system for calculating the position of input/output terminals (HB) of an IC chip (IC) picked up by the IC moving system (410) from the image information captured by the first camera and second camera and identifying the relative position of the IC chip (IC) picked up by the IC moving system (410) with respect to a contact unit based on the results of calculation, wherein the IC moving system (410) corrects the position of the IC chip based on the relative position of the input/output terminals (HB) of the IC chip (IC) with respect to the contact unit identified by the image processing system.